

INTERCONNECTS

SERIES 830, 831, 832, 833 • 2mm GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

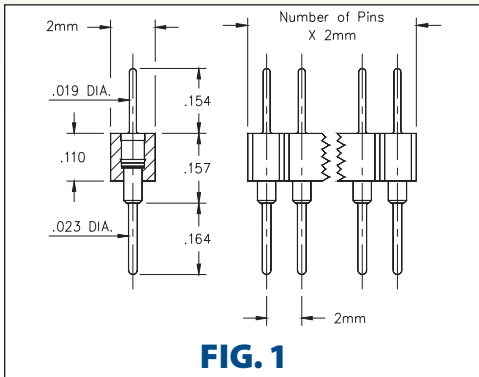


FIG. 1

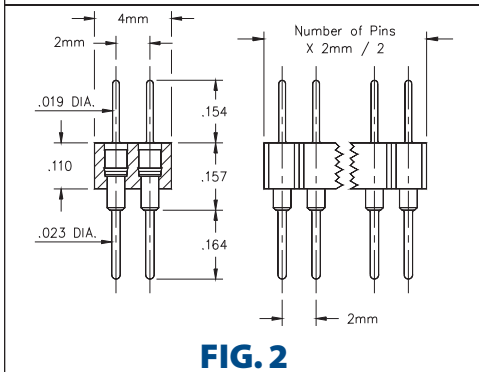


FIG. 2

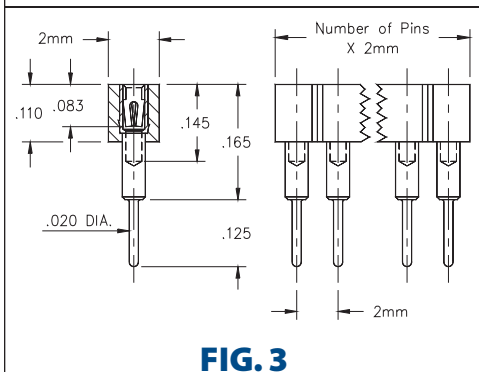


FIG. 3

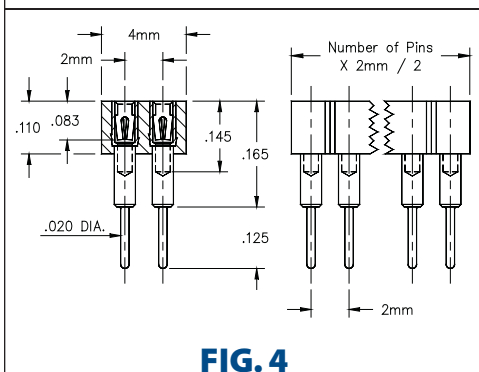


FIG. 4

- Series 830 single & double row interconnects have 2mm pin spacing and permit board stacking as low as .322"
- Pin headers (830 & 832 series) use MM #5012 pins. See page 208 for details
- Sockets (831 & 833 series) use MM #1802 receptacles and accept pin diameters from .015"-.025". See page 169 for details
- Contact is rated at 3 amps
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION










FIG. 1	Series 830...001	Single Row Pin Header		
	830-XX-0	-10-001000	Specify number of pins 01-50	
FIG. 2	Series 832...001	Double Row Pin Header		
	832-XX-	-10-001000	Specify number of pins 002-100	
  				
SPECIFY PLATING CODE XX=				
Pin Plating 				
	10 μ Au	90	40 μ Sn	
	10 μ Au	200 μ Sn/Pb	200 μ Sn	

FIG. 3	Series 831...001	Single Row Socket			
	831-XX-0	-10-001000	Specify number of pins 01-50		
FIG. 4	Series 833...001	Double Row Socket			
	833-XX-	-10-001000	Specify number of pins 002-100		
  					
SPECIFY PLATING CODE XX=					
Sleeve (Pin) 					
Contact (Clip) 					
		91	93	41 μ Sn	43 μ Sn
		200 μ Sn/Pb	200 μ Sn/Pb	200 μ Sn	200 μ Sn
		10 μ Au	30 μ Au	10 μ Au	30 μ Au